Welcome to [E-XFL.COM](#)**Understanding Embedded - FPGAs (Field Programmable Gate Array)**

Embedded - FPGAs, or Field Programmable Gate Arrays, are advanced integrated circuits that offer unparalleled flexibility and performance for digital systems. Unlike traditional fixed-function logic devices, FPGAs can be programmed and reprogrammed to execute a wide array of logical operations, enabling customized functionality tailored to specific applications. This reprogrammability allows developers to iterate designs quickly and implement complex functions without the need for custom hardware.

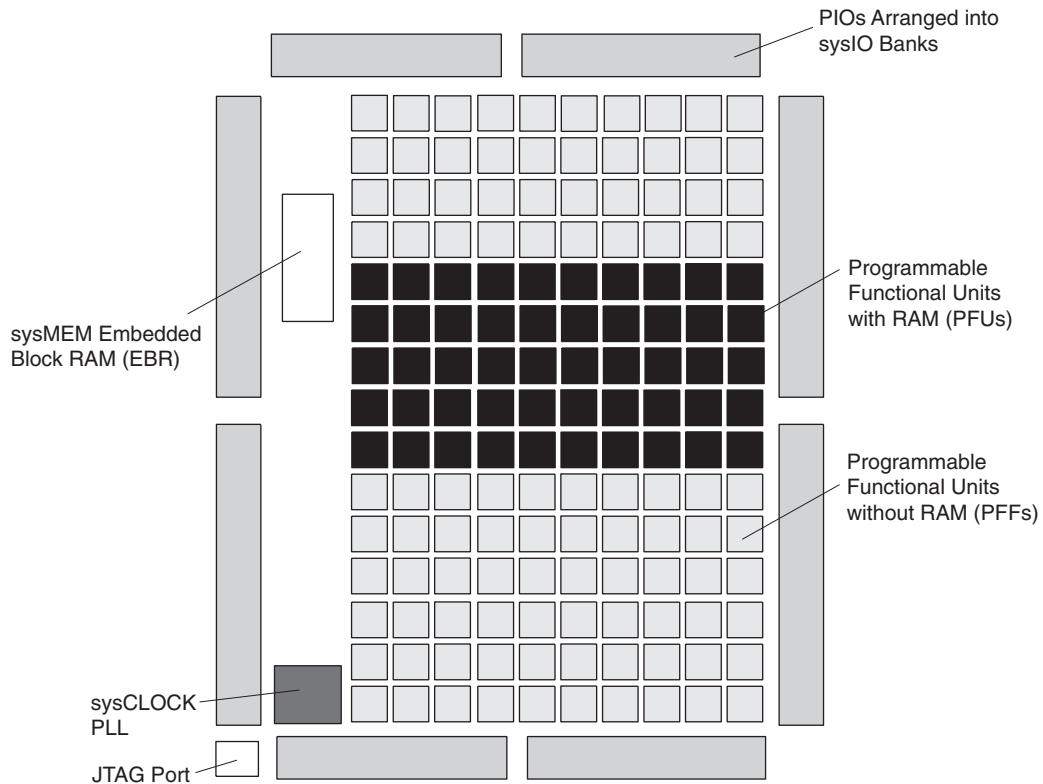
Applications of Embedded - FPGAs

The versatility of Embedded - FPGAs makes them indispensable in numerous fields. In telecommunications.

Details

Product Status	Obsolete
Number of LABs/CLBs	80
Number of Logic Elements/Cells	640
Total RAM Bits	-
Number of I/O	101
Number of Gates	-
Voltage - Supply	1.71V ~ 3.465V
Mounting Type	Surface Mount
Operating Temperature	0°C ~ 85°C (TJ)
Package / Case	132-LFBGA, CSPBGA
Supplier Device Package	132-CSPBGA (8x8)
Purchase URL	https://www.e-xfl.com/product-detail/lattice-semiconductor/lcmxo640c-5m132c

Figure 2-1. Top View of the MachXO1200 Device¹



1. Top view of the MachXO2280 device is similar but with higher LUT count, two PLLs, and three EBR blocks.

Figure 2-2. Top View of the MachXO640 Device

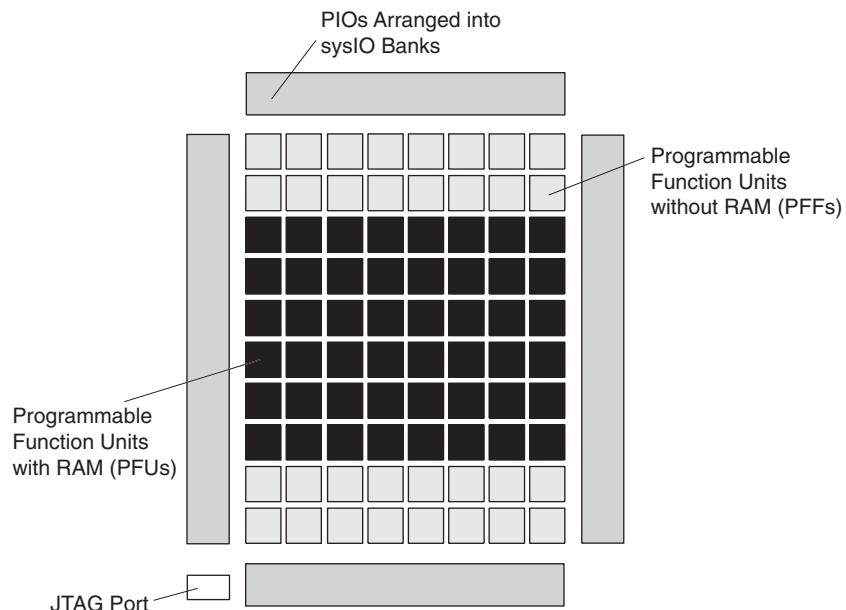
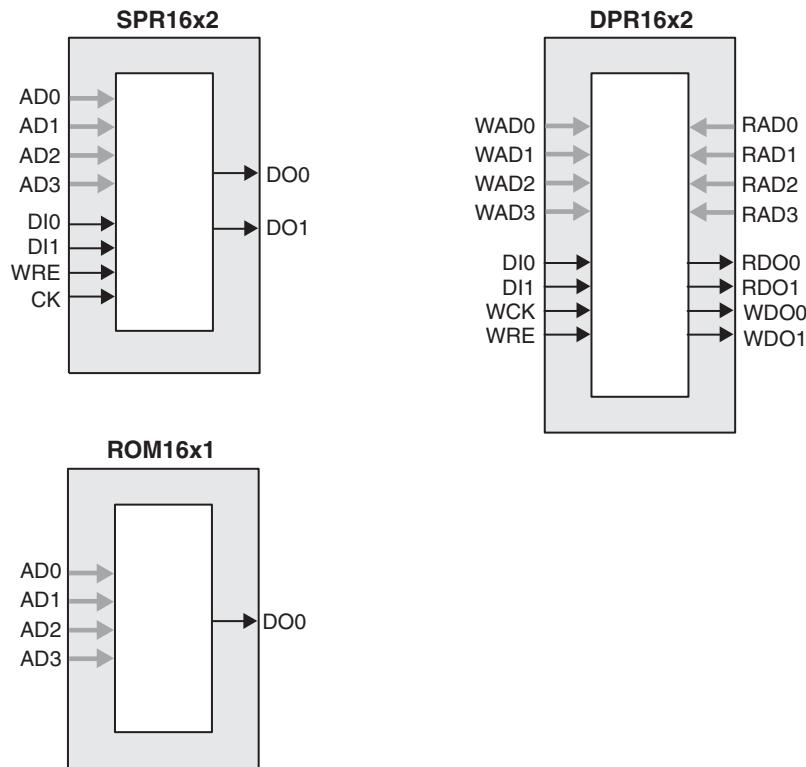


Figure 2-6. Distributed Memory Primitives



ROM Mode: The ROM mode uses the same principal as the RAM modes, but without the Write port. Pre-loading is accomplished through the programming interface during configuration.

PFU Modes of Operation

Slices can be combined within a PFU to form larger functions. Table 2-4 tabulates these modes and documents the functionality possible at the PFU level.

Table 2-4. PFU Modes of Operation

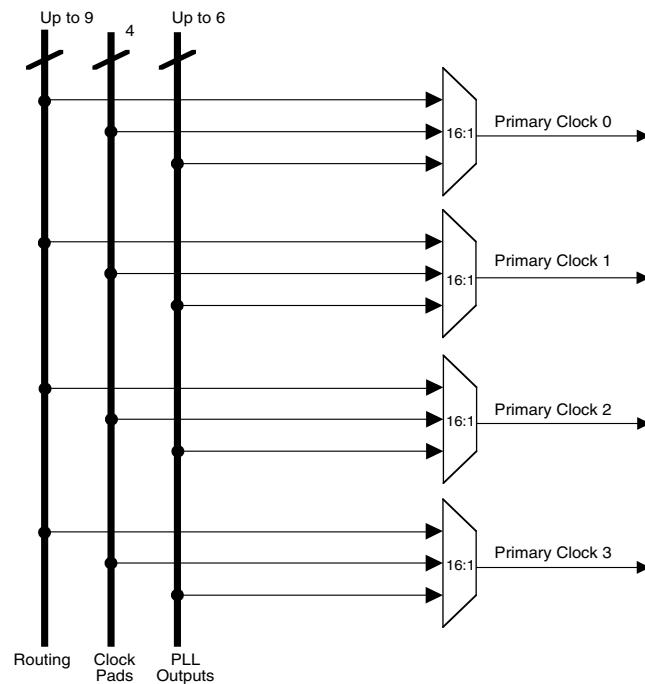
Logic	Ripple	RAM	ROM
LUT 4x8 or MUX 2x1 x 8	2-bit Add x 4	SPR16x2 x 4 DPR16x2 x 2	ROM16x1 x 8
LUT 5x4 or MUX 4x1 x 4	2-bit Sub x 4	SPR16x4 x 2 DPR16x4 x 1	ROM16x2 x 4
LUT 6x2 or MUX 8x1 x 2	2-bit Counter x 4	SPR16x8 x 1	ROM16x4 x 2
LUT 7x1 or MUX 16x1 x 1	2-bit Comp x 4		ROM16x8 x 1

Routing

There are many resources provided in the MachXO devices to route signals individually or as buses with related control signals. The routing resources consist of switching circuitry, buffers and metal interconnect (routing) segments.

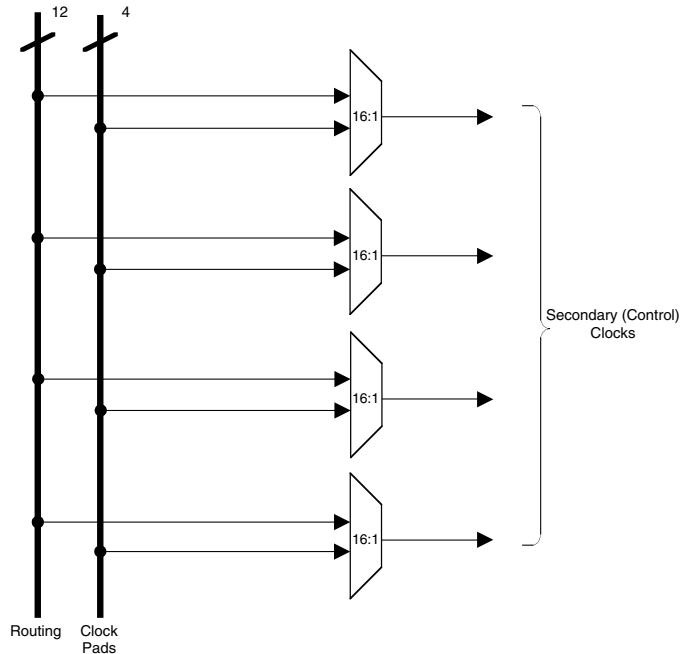
The inter-PFU connections are made with three different types of routing resources: x1 (spans two PFUs), x2 (spans three PFUs) and x6 (spans seven PFUs). The x1, x2, and x6 connections provide fast and efficient connections in the horizontal and vertical directions.

Figure 2-8. Primary Clocks for MachXO1200 and MachXO2280 Devices



Four secondary clocks are generated from four 16:1 muxes as shown in Figure 2-9. Four of the secondary clock sources come from dual function clock pins and 12 come from internal routing.

Figure 2-9. Secondary Clocks for MachXO Devices



PIO Groups

On the MachXO devices, PIO cells are assembled into two different types of PIO groups, those with four PIO cells and those with six PIO cells. PIO groups with four IOs are placed on the left and right sides of the device while PIO groups with six IOs are placed on the top and bottom. The individual PIO cells are connected to their respective sysIO buffers and PADs.

On all MachXO devices, two adjacent PIOs can be joined to provide a complementary Output driver pair. The I/O pin pairs are labeled as "T" and "C" to distinguish between the true and complement pins.

The MachXO1200 and MachXO2280 devices contain enhanced I/O capability. All PIO pairs on these larger devices can implement differential receivers. In addition, half of the PIO pairs on the left and right sides of these devices can be configured as LVDS transmit/receive pairs. PIOs on the top of these larger devices also provide PCI support.

Figure 2-15. Group of Four Programmable I/O Cells

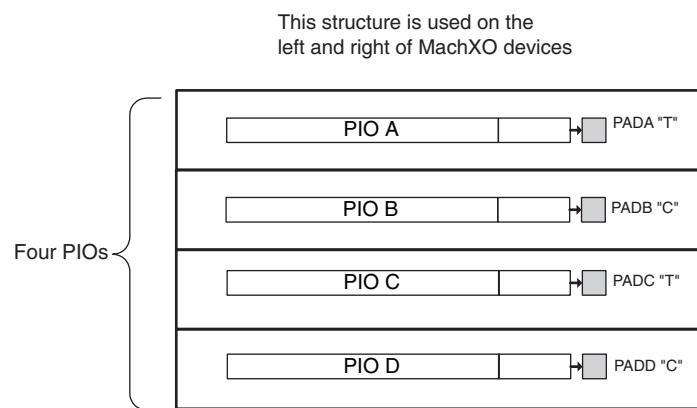
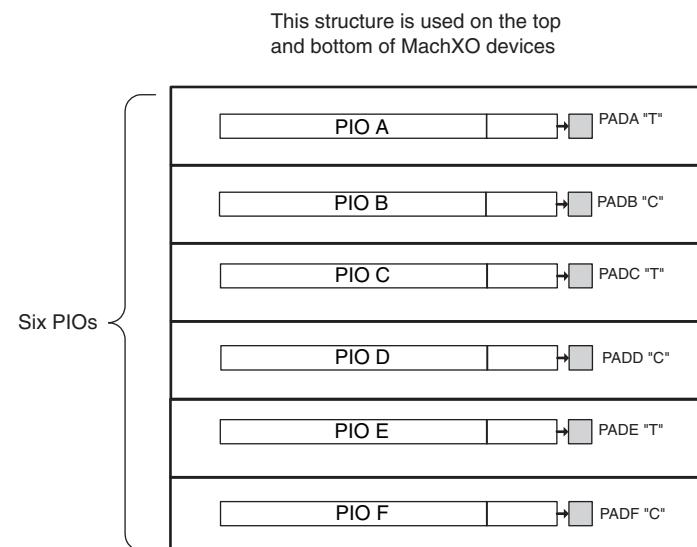


Figure 2-16. Group of Six Programmable I/O Cells



PIO

The PIO blocks provide the interface between the sysIO buffers and the internal PFU array blocks. These blocks receive output data from the PFU array and a fast output data signal from adjacent PFUs. The output data and fast

of the devices also support differential input buffers. PCI clamps are available on the top Bank I/O buffers. The PCI clamp is enabled after V_{CC} , V_{CCAUX} , and V_{CCIO} are at valid operating levels and the device has been configured.

The two pads in the pair are described as “true” and “comp”, where the true pad is associated with the positive side of the differential input buffer and the comp (complementary) pad is associated with the negative side of the differential input buffer.

2. Left and Right sysIO Buffer Pairs

The sysIO buffer pairs in the left and right Banks of the device consist of two single-ended output drivers and two sets of single-ended input buffers (supporting ratioed and absolute input levels). The devices also have a differential driver per output pair. The referenced input buffer can also be configured as a differential input buffer. In these Banks the two pads in the pair are described as “true” and “comp”, where the true pad is associated with the positive side of the differential I/O, and the comp (complementary) pad is associated with the negative side of the differential I/O.

Typical I/O Behavior During Power-up

The internal power-on-reset (POR) signal is deactivated when V_{CC} and V_{CCAUX} have reached satisfactory levels. After the POR signal is deactivated, the FPGA core logic becomes active. It is the user's responsibility to ensure that all V_{CCIO} Banks are active with valid input logic levels to properly control the output logic states of all the I/O Banks that are critical to the application. The default configuration of the I/O pins in a blank device is tri-state with a weak pull-up to V_{CCIO} . The I/O pins will maintain the blank configuration until V_{CC} , V_{CCAUX} and V_{CCIO} have reached satisfactory levels at which time the I/Os will take on the user-configured settings.

The V_{CC} and V_{CCAUX} supply the power to the FPGA core fabric, whereas the V_{CCIO} supplies power to the I/O buffers. In order to simplify system design while providing consistent and predictable I/O behavior, the I/O buffers should be powered up along with the FPGA core fabric. Therefore, V_{CCIO} supplies should be powered up before or together with the V_{CC} and V_{CCAUX} supplies.

Supported Standards

The MachXO sysIO buffer supports both single-ended and differential standards. Single-ended standards can be further subdivided into LVCMOS and LVTTL. The buffer supports the LVTTL, LVCMOS 1.2, 1.5, 1.8, 2.5, and 3.3V standards. In the LVCMOS and LVTTL modes, the buffer has individually configurable options for drive strength, bus maintenance (weak pull-up, weak pull-down, bus-keeper latch or none) and open drain. BLVDS and LVPECL output emulation is supported on all devices. The MachXO1200 and MachXO2280 support on-chip LVDS output buffers on approximately 50% of the I/Os on the left and right Banks. Differential receivers for LVDS, BLVDS and LVPECL are supported on all Banks of MachXO1200 and MachXO2280 devices. PCI support is provided in the top Banks of the MachXO1200 and MachXO2280 devices. Table 2-8 summarizes the I/O characteristics of the devices in the MachXO family.

Tables 2-9 and 2-10 show the I/O standards (together with their supply and reference voltages) supported by the MachXO devices. For further information on utilizing the sysIO buffer to support a variety of standards please see the details of additional technical documentation at the end of this data sheet.

Table 2-8. I/O Support Device by Device

	MachXO256	MachXO640	MachXO1200	MachXO2280
Number of I/O Banks	2	4	8	8
Type of Input Buffers	Single-ended (all I/O Banks)	Single-ended (all I/O Banks)	Single-ended (all I/O Banks) Differential Receivers (all I/O Banks)	Single-ended (all I/O Banks) Differential Receivers (all I/O Banks)
Types of Output Buffers	Single-ended buffers with complementary outputs (all I/O Banks)	Single-ended buffers with complementary outputs (all I/O Banks)	Single-ended buffers with complementary outputs (all I/O Banks) Differential buffers with true LVDS outputs (50% on left and right side)	Single-ended buffers with complementary outputs (all I/O Banks) Differential buffers with true LVDS outputs (50% on left and right side)
Differential Output Emulation Capability	All I/O Banks	All I/O Banks	All I/O Banks	All I/O Banks
PCI Support	No	No	Top side only	Top side only

Table 2-9. Supported Input Standards

Input Standard	VCCIO (Typ.)				
	3.3V	2.5V	1.8V	1.5V	1.2V
Single Ended Interfaces					
LVTTL	Yes	Yes	Yes	Yes	Yes
LVCMOS33	Yes	Yes	Yes	Yes	Yes
LVCMOS25	Yes	Yes	Yes	Yes	Yes
LVCMOS18			Yes		
LVCMOS15				Yes	
LVCMOS12	Yes	Yes	Yes	Yes	Yes
PCI ¹	Yes				
Differential Interfaces					
BLVDS ² , LVDS ² , LVPECL ² , RSDS ²	Yes	Yes	Yes	Yes	Yes

1. Top Banks of MachXO1200 and MachXO2280 devices only.

2. MachXO1200 and MachXO2280 devices only.

Table 2-10. Supported Output Standards

Output Standard	Drive	V_{CCIO} (Typ.)
Single-ended Interfaces		
LV TTL	4mA, 8mA, 12mA, 16mA	3.3
LVC MOS33	4mA, 8mA, 12mA, 14mA	3.3
LVC MOS25	4mA, 8mA, 12mA, 14mA	2.5
LVC MOS18	4mA, 8mA, 12mA, 14mA	1.8
LVC MOS15	4mA, 8mA	1.5
LVC MOS12	2mA, 6mA	1.2
LVC MOS33, Open Drain	4mA, 8mA, 12mA, 14mA	—
LVC MOS25, Open Drain	4mA, 8mA, 12mA, 14mA	—
LVC MOS18, Open Drain	4mA, 8mA, 12mA, 14mA	—
LVC MOS15, Open Drain	4mA, 8mA	—
LVC MOS12, Open Drain	2mA, 6mA	—
PCI33 ³	N/A	3.3
Differential Interfaces		
LVDS ^{1,2}	N/A	2.5
BLVDS, RS DS ²	N/A	2.5
LVPECL ²	N/A	3.3

1. MachXO1200 and MachXO2280 devices have dedicated LVDS buffers.

2. These interfaces can be emulated with external resistors in all devices.

3. Top Banks of MachXO1200 and MachXO2280 devices only.

sysIO Buffer Banks

The number of Banks vary between the devices of this family. Eight Banks surround the two larger devices, the MachXO1200 and MachXO2280 (two Banks per side). The MachXO640 has four Banks (one Bank per side). The smallest member of this family, the MachXO256, has only two Banks.

Each sysIO buffer Bank is capable of supporting multiple I/O standards. Each Bank has its own I/O supply voltage (V_{CCIO}) which allows it to be completely independent from the other Banks. Figure 2-18, Figure 2-18, Figure 2-20 and Figure 2-21 shows the sysIO Banks and their associated supplies for all devices.

Figure 2-20. MachXO640 Banks

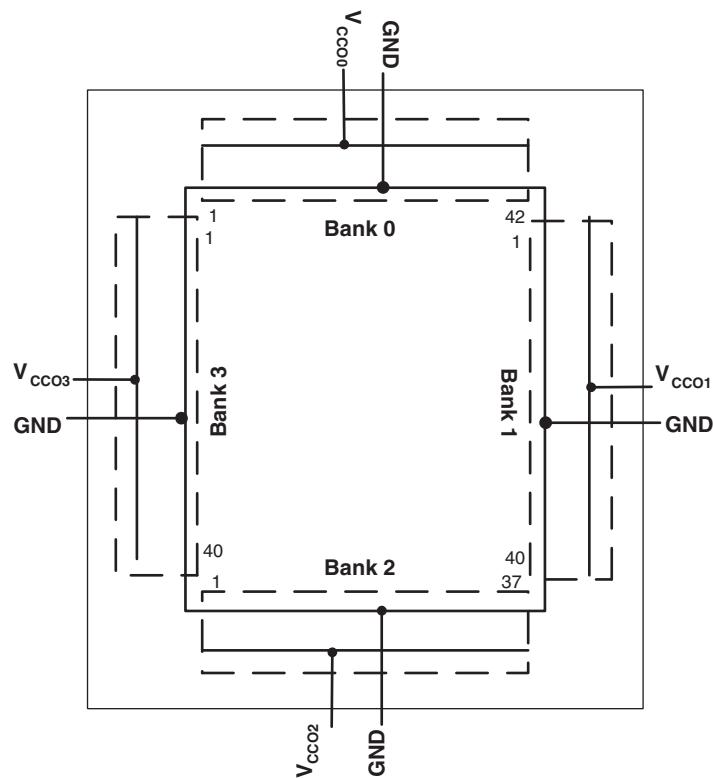
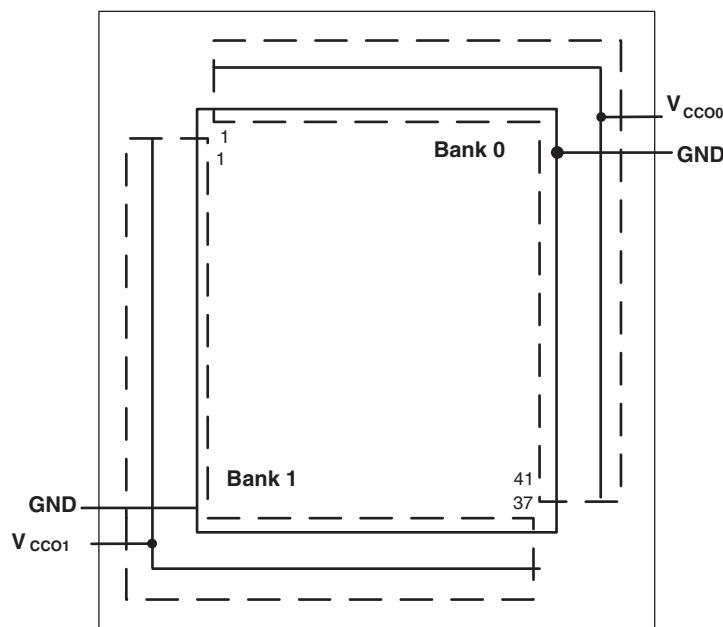


Figure 2-21. MachXO256 Banks



Hot Socketing

The MachXO devices have been carefully designed to ensure predictable behavior during power-up and power-down. Leakage into I/O pins is controlled to within specified limits. This allows for easy integration with the rest of

MachXO256 and MachXO640 Hot Socketing Specifications^{1, 2, 3}

Symbol	Parameter	Condition	Min.	Typ.	Max	Units
I_{DK}	Input or I/O leakage Current	$0 \leq V_{IN} \leq V_{IH}$ (MAX)	—	—	+/-1000	μA

1. Insensitive to sequence of V_{CC} , V_{CCAUX} , and V_{CCIO} . However, assumes monotonic rise/fall rates for V_{CC} , V_{CCAUX} , and V_{CCIO} .

2. $0 \leq V_{CC} \leq V_{CC}$ (MAX), $0 \leq V_{CCIO} \leq V_{CCIO}$ (MAX) and $0 \leq V_{CCAUX} \leq V_{CCAUX}$ (MAX).

3. I_{DK} is additive to I_{PU} , I_{PD} or I_{BH} .

MachXO1200 and MachXO2280 Hot Socketing Specifications^{1, 2, 3}

Symbol	Parameter	Condition	Min.	Typ.	Max.	Units
Non-LVDS General Purpose sysIos						
I_{DK}	Input or I/O Leakage Current	$0 \leq V_{IN} \leq V_{IH}$ (MAX.)	—	—	+/-1000	μA
LVDS General Purpose sysIos						
I_{DK_LVDS}	Input or I/O Leakage Current	$V_{IN} \leq V_{CCIO}$	—	—	+/-1000	μA
		$V_{IN} > V_{CCIO}$	—	35	—	mA

1. Insensitive to sequence of V_{CC} , V_{CCAUX} , and V_{CCIO} . However, assumes monotonic rise/fall rates for V_{CC} , V_{CCAUX} , and V_{CCIO} .

2. $0 \leq V_{CC} \leq V_{CC}$ (MAX), $0 \leq V_{CCIO} \leq V_{CCIO}$ (MAX), and $0 \leq V_{CCAUX} \leq V_{CCAUX}$ (MAX).

3. I_{DK} is additive to I_{PU} , I_{PW} or I_{BH} .

DC Electrical Characteristics

Over Recommended Operating Conditions

Symbol	Parameter	Condition	Min.	Typ.	Max.	Units
I_{IL}, I_{IH} ^{1, 4, 5}	Input or I/O Leakage	$0 \leq V_{IN} \leq (V_{CCIO} - 0.2V)$	—	—	10	μA
		$(V_{CCIO} - 0.2V) < V_{IN} \leq 3.6V$	—	—	40	μA
I_{PU}	I/O Active Pull-up Current	$0 \leq V_{IN} \leq 0.7 V_{CCIO}$	-30	—	-150	μA
I_{PD}	I/O Active Pull-down Current	V_{IL} (MAX) $\leq V_{IN} \leq V_{IH}$ (MAX)	30	—	150	μA
$I_{B HLS}$	Bus Hold Low sustaining current	$V_{IN} = V_{IL}$ (MAX)	30	—	—	μA
$I_{B HHS}$	Bus Hold High sustaining current	$V_{IN} = 0.7V_{CCIO}$	-30	—	—	μA
$I_{B HLO}$	Bus Hold Low Overdrive current	$0 \leq V_{IN} \leq V_{IH}$ (MAX)	—	—	150	μA
$I_{B HHO}$	Bus Hold High Overdrive current	$0 \leq V_{IN} \leq V_{IH}$ (MAX)	—	—	-150	μA
V_{BHT} ³	Bus Hold trip Points	$0 \leq V_{IN} \leq V_{IH}$ (MAX)	V_{IL} (MAX)	—	V_{IH} (MIN)	V
C1	I/O Capacitance ²	$V_{CCIO} = 3.3V, 2.5V, 1.8V, 1.5V, 1.2V$, $V_{CC} = \text{Typ.}$, $V_{IO} = 0$ to V_{IH} (MAX)	—	8	—	pf
C2	Dedicated Input Capacitance ²	$V_{CCIO} = 3.3V, 2.5V, 1.8V, 1.5V, 1.2V$, $V_{CC} = \text{Typ.}$, $V_{IO} = 0$ to V_{IH} (MAX)	—	8	—	pf

1. Input or I/O leakage current is measured with the pin configured as an input or as an I/O with the output driver tri-stated. It is not measured with the output driver active. Bus maintenance circuits are disabled.

2. T_A 25°C, $f = 1.0MHz$

3. Please refer to V_{IL} and V_{IH} in the sysIO Single-Ended DC Electrical Characteristics table of this document.

4. Not applicable to SLEEPN pin.

5. When V_{IH} is higher than V_{CCIO} , a transient current typically of 30ns in duration or less with a peak current of 6mA can occur on the high-to-low transition. For MachXO1200 and MachXO2280 true LVDS output pins, V_{IH} must be less than or equal to V_{CCIO} .

Supply Current (Sleep Mode)^{1,2}

Symbol	Parameter	Device	Typ. ³	Max.	Units
I_{CC}	Core Power Supply	LCMxo256C	12	25	μA
		LCMxo640C	12	25	μA
		LCMxo1200C	12	25	μA
		LCMxo2280C	12	25	μA
I_{CCAUX}	Auxiliary Power Supply	LCMxo256C	1	15	μA
		LCMxo640C	1	25	μA
		LCMxo1200C	1	45	μA
		LCMxo2280C	1	85	μA
I_{CCIO}	Bank Power Supply ⁴	All LCMxo 'C' Devices	2	30	μA

1. Assumes all inputs are configured as LVCMOS and held at the VCCIO or GND.

2. Frequency = 0MHz.

3. $T_A = 25^\circ C$, power supplies at nominal voltage.

4. Per Bank.

Supply Current (Standby)^{1, 2, 3, 4}

Over Recommended Operating Conditions

Symbol	Parameter	Device	Typ. ⁵	Units
I_{CC}	Core Power Supply	LCMxo256C	7	mA
		LCMxo640C	9	mA
		LCMxo1200C	14	mA
		LCMxo2280C	20	mA
		LCMxo256E	4	mA
		LCMxo640E	6	mA
		LCMxo1200E	10	mA
		LCMxo2280E	12	mA
I_{CCAUX}	Auxiliary Power Supply $V_{CCAUX} = 3.3V$	LCMxo256E/C	5	mA
		LCMxo640E/C	7	mA
		LCMxo1200E/C	12	mA
		LCMxo2280E/C	13	mA
I_{CCIO}	Bank Power Supply ⁶	All devices	2	mA

1. For further information on supply current, please see details of additional technical documentation at the end of this data sheet.

2. Assumes all outputs are tristated, all inputs are configured as LVCMOS and held at V_{CCIO} or GND.

3. Frequency = 0MHz.

4. User pattern = blank.

5. $T_J = 25^\circ C$, power supplies at nominal voltage.

6. Per Bank. $V_{CCIO} = 2.5V$. Does not include pull-up/pull-down.

sysIO Recommended Operating Conditions

Standard	V_{CCIO} (V)		
	Min.	Typ.	Max.
LVC MOS 3.3	3.135	3.3	3.465
LVC MOS 2.5	2.375	2.5	2.625
LVC MOS 1.8	1.71	1.8	1.89
LVC MOS 1.5	1.425	1.5	1.575
LVC MOS 1.2	1.14	1.2	1.26
LV TTL	3.135	3.3	3.465
PCI ³	3.135	3.3	3.465
LVDS ^{1,2}	2.375	2.5	2.625
LVPECL ¹	3.135	3.3	3.465
BLVDS ¹	2.375	2.5	2.625
RS DS ¹	2.375	2.5	2.625

1. Inputs on chip. Outputs are implemented with the addition of external resistors.

2. MachXO1200 and MachXO2280 devices have dedicated LVDS buffers

3. Input on the top bank of the MachXO1200 and MachXO2280 only.

sysIO Single-Ended DC Electrical Characteristics

Input/Output Standard	V_{IL}		V_{IH}		V_{OL} Max. (V)	V_{OH} Min. (V)	I_{OL} ¹ (mA)	I_{OH} ¹ (mA)
	Min. (V)	Max. (V)	Min. (V)	Max. (V)				
LVC MOS 3.3	-0.3	0.8	2.0	3.6	0.4	V_{CCIO} - 0.4	16, 12, 8, 4	-14, -12, -8, -4
					0.2	V_{CCIO} - 0.2	0.1	-0.1
LV TTL	-0.3	0.8	2.0	3.6	0.4	2.4	16	-16
					0.4	V_{CCIO} - 0.4	12, 8, 4	-12, -8, -4
					0.2	V_{CCIO} - 0.2	0.1	-0.1
LVC MOS 2.5	-0.3	0.7	1.7	3.6	0.4	V_{CCIO} - 0.4	16, 12, 8, 4	-14, -12, -8, -4
					0.2	V_{CCIO} - 0.2	0.1	-0.1
LVC MOS 1.8	-0.3	$0.35V_{CCIO}$	$0.65V_{CCIO}$	3.6	0.4	V_{CCIO} - 0.4	16, 12, 8, 4	-14, -12, -8, -4
					0.2	V_{CCIO} - 0.2	0.1	-0.1
LVC MOS 1.5	-0.3	$0.35V_{CCIO}$	$0.65V_{CCIO}$	3.6	0.4	V_{CCIO} - 0.4	8, 4	-8, -4
					0.2	V_{CCIO} - 0.2	0.1	-0.1
LVC MOS 1.2 ("C" Version)	-0.3	0.42	0.78	3.6	0.4	V_{CCIO} - 0.4	6, 2	-6, -2
					0.2	V_{CCIO} - 0.2	0.1	-0.1
LVC MOS 1.2 ("E" Version)	-0.3	$0.35V_{CC}$	$0.65V_{CC}$	3.6	0.4	V_{CCIO} - 0.4	6, 2	-6, -2
					0.2	V_{CCIO} - 0.2	0.1	-0.1
PCI	-0.3	$0.3V_{CCIO}$	$0.5V_{CCIO}$	3.6	$0.1V_{CCIO}$	$0.9V_{CCIO}$	1.5	-0.5

1. The average DC current drawn by I/Os between GND connections, or between the last GND in an I/O Bank and the end of an I/O Bank, as shown in the logic signal connections table shall not exceed $n * 8\text{mA}$. Where n is the number of I/Os between Bank GND connections or between the last GND in a Bank and the end of a Bank.

Typical Building Block Function Performance¹

Pin-to-Pin Performance (LVCMS25 12mA Drive)

Function	-5 Timing	Units
Basic Functions		
16-bit decoder	6.7	ns
4:1 MUX	4.5	ns
16:1 MUX	5.1	ns

Register-to-Register Performance

Function	-5 Timing	Units
Basic Functions		
16:1 MUX	487	MHz
16-bit adder	292	MHz
16-bit counter	388	MHz
64-bit counter	200	MHz
Embedded Memory Functions (1200 and 2280 Devices Only)		
256x36 Single Port RAM	284	MHz
512x18 True-Dual Port RAM	284	MHz
Distributed Memory Functions		
16x2 Single Port RAM	434	MHz
64x2 Single Port RAM	320	MHz
128x4 Single Port RAM	261	MHz
32x2 Pseudo-Dual Port RAM	314	MHz
64x4 Pseudo-Dual Port RAM	271	MHz

1. The above timing numbers are generated using the ispLEVER design tool. Exact performance may vary with device and tool version. The tool uses internal parameters that have been characterized but are not tested on every device.

Rev. A 0.19

Derating Logic Timing

Logic Timing provided in the following sections of the data sheet and the ispLEVER design tools are worst case numbers in the operating range. Actual delays may be much faster. The ispLEVER design tool from Lattice can provide logic timing numbers at a particular temperature and voltage.

LCMxo256 and LCMxo640 Logic Signal Connections: 100 TQFP (Cont.)

Pin Number	LCMxo256				LCMxo640			
	Ball Function	Bank	Dual Function	Differential	Ball Function	Bank	Dual Function	Differential
43	PB4A	1		T	PB8B	2		
44	PB4B	1		C	PB8C	2		T
45	PB4C	1		T	PB8D	2		C
46	PB4D	1		C	PB9A	2		
47	PB5A	1			PB9C	2		T
48*	SLEEPN	-	SLEEPN		SLEEPN	-	SLEEPN	
49	PB5C	1		T	PB9D	2		C
50	PB5D	1		C	PB9F	2		
51	PR9B	0		C	PR11D	1		C
52	PR9A	0		T	PR11B	1		C
53	PR8B	0		C	PR11C	1		T
54	PR8A	0		T	PR11A	1		T
55	PR7D	0		C	PR10D	1		C
56	PR7C	0		T	PR10C	1		T
57	PR7B	0		C	PR10B	1		C
58	PR7A	0		T	PR10A	1		T
59	PR6B	0		C	PR9D	1		
60	VCCIO0	0			VCCIO1	1		
61	PR6A	0		T	PR9B	1		
62	GNDIO0	0			GNDIO1	1		
63	PR5D	0		C	PR7B	1		
64	PR5C	0		T	PR6C	1		
65	PR5B	0		C	PR6B	1		
66	PR5A	0		T	PR5D	1		
67	PR4B	0		C	PR5B	1		
68	PR4A	0		T	PR4D	1		
69	PR3D	0		C	PR4B	1		
70	PR3C	0		T	PR3D	1		
71	PR3B	0		C	PR3B	1		
72	PR3A	0		T	PR2D	1		
73	PR2B	0		C	PR2B	1		
74	VCCIO0	0			VCCIO1	1		
75	GNDIO0	0			GNDIO1	1		
76	PR2A	0		T	PT9F	0		C
77	PT5C	0			PT9E	0		T
78	PT5B	0		C	PT9C	0		
79	PT5A	0		T	PT9A	0		
80	PT4F	0		C	VCCIO0	0		
81	PT4E	0		T	GNDIO0	0		
82	PT4D	0		C	PT7E	0		
83	PT4C	0		T	PT7A	0		
84	GND	-			GND	-		

LCMxo256 and LCMxo640 Logic Signal Connections: 100 TQFP (Cont.)

Pin Number	LCMxo256				LCMxo640			
	Ball Function	Bank	Dual Function	Differential	Ball Function	Bank	Dual Function	Differential
85	PT4B	0	PCLK0_1**	C	PT6B	0	PCLK0_1**	
86	PT4A	0	PCLK0_0**	T	PT5B	0	PCLK0_0**	C
87	PT3D	0		C	PT5A	0		T
88	VCCAUX	-			VCCAUX	-		
89	PT3C	0		T	PT4F	0		
90	VCC	-			VCC	-		
91	PT3B	0		C	PT3F	0		
92	VCCIO0	0			VCCIO0	0		
93	GNDIO0	0			GNDIO0	0		
94	PT3A	0		T	PT3B	0		C
95	PT2F	0		C	PT3A	0		T
96	PT2E	0		T	PT2F	0		C
97	PT2D	0		C	PT2E	0		T
98	PT2C	0		T	PT2B	0		C
99	PT2B	0		C	PT2C	0		
100	PT2A	0		T	PT2A	0		T

* NC for "E" devices.

** Primary clock inputs are single-ended.

LCMxo256 and LCMxo640 Logic Signal Connections: 100 csBGA (Cont.)

LCMxo256					LCMxo640				
Ball Number	Ball Function	Bank	Dual Function	Differential	Ball Number	Ball Function	Bank	Dual Function	Differential
P13	PB5A	1			P13	PB9C	2		T
M12*	SLEEPN	-	SLEEPN		M12*	SLEEPN	-	SLEEPN	
P14	PB5C	1		T	P14	PB9D	2		C
N13	PB5D	1		C	N13	PB9F	2		
N14	PR9B	0		C	N14	PR11D	1		C
M14	PR9A	0		T	M14	PR11B	1		C
L13	PR8B	0		C	L13	PR11C	1		T
L14	PR8A	0		T	L14	PR11A	1		T
M13	PR7D	0		C	M13	PR10D	1		C
K14	PR7C	0		T	K14	PR10C	1		T
K13	PR7B	0		C	K13	PR10B	1		C
J14	PR7A	0		T	J14	PR10A	1		T
J13	PR6B	0		C	J13	PR9D	1		
H13	PR6A	0		T	H13	PR9B	1		
G14	GNDIO0	0			G14	GNDIO1	1		
G13	PR5D	0		C	G13	PR7B	1		
F14	PR5C	0		T	F14	PR6C	1		
F13	PR5B	0		C	F13	PR6B	1		
E14	PR5A	0		T	E14	PR5D	1		
E13	PR4B	0		C	E13	PR5B	1		
D14	PR4A	0		T	D14	PR4D	1		
D13	PR3D	0		C	D13	PR4B	1		
C14	PR3C	0		T	C14	PR3D	1		
C13	PR3B	0		C	C13	PR3B	1		
B14	PR3A	0		T	B14	PR2D	1		
C12	PR2B	0		C	C12	PR2B	1		
B13	GNDIO0	0			B13	GNDIO1	1		
A13	PR2A	0		T	A13	PT9F	0		C
A12	PT5C	0			A12	PT9E	0		T
B11	PT5B	0		C	B11	PT9C	0		
A11	PT5A	0		T	A11	PT9A	0		
B12	PT4F	0		C	B12	VCCIO0	0		
A10	PT4E	0		T	A10	GNDIO0	0		
B10	PT4D	0		C	B10	PT7E	0		
A9	PT4C	0		T	A9	PT7A	0		
A8	PT4B	0	PCLK0_1**	C	A8	PT6B	0	PCLK0_1**	
B8	PT4A	0	PCLK0_0**	T	B8	PT5B	0	PCLK0_0**	C
A7	PT3D	0		C	A7	PT5A	0		T
B7	VCCAUX	-			B7	VCCAUX	-		
A6	PT3C	0		T	A6	PT4F	0		
B6	VCC	-			B6	VCC	-		
A5	PT3B	0		C	A5	PT3F	0		

**LCMxo640, LCMxo1200 and LCMxo2280 Logic Signal Connections:
 256 caBGA / 256 ftBGA (Cont.)**

LCMxo640					LCMxo1200					LCMxo2280				
Ball Number	Ball Function	Bank	Dual Function	Differential	Ball Number	Ball Function	Bank	Dual Function	Differential	Ball Number	Ball Function	Bank	Dual Function	Differential
J13	PR8C	1		T	J13	PR11A	3			J13	PR14A	3		T*
GND	GND	-			GND	GND	-			GND	GND	-		
K14	PR8B	1		C	K14	PR10D	3			K14	PR13D	3		C
J14	PR8A	1		T	J14	PR10C	3			J14	PR13C	3		T
K15	PR7D	1		C	K15	PR10B	3			K15	PR13B	3		C*
J15	PR7C	1		T	J15	PR10A	3			J15	PR13A	3		T*
-	-				GND	GNDIO3	3			GND	GNDIO3	3		
-	-				VCCIO3	VCCIO3	3			VCCIO3	VCCIO3	3		
K12	NC				K12	PR9D	3			K12	PR11D	3		C
J12	NC				J12	PR9C	3			J12	PR11C	3		T
J16	PR7B	1		C	J16	PR9B	3			J16	PR11B	3		C*
H16	PR7A	1		T	H16	PR9A	3			H16	PR11A	3		T*
H15	PR6B	1		C	H15	PR8D	2			H15	PR10D	2		C
G15	PR6A	1		T	G15	PR8C	2			G15	PR10C	2		T
H14	PR5D	1		C	H14	PR8B	2			H14	PR10B	2		C*
G14	PR5C	1		T	G14	PR8A	2			G14	PR10A	2		T*
GND	GNDIO1	1			GND	GNDIO2	2			GND	GNDIO2	2		
VCCIO1	VCCIO1	1			VCCIO2	VCCIO2	2			VCCIO2	VCCIO2	2		
H13	PR6D	1		C	H13	PR7D	2			H13	PR9D	2		C
H12	PR6C	1		T	H12	PR7C	2			H12	PR9C	2		T
G13	PR4D	1		C	G13	PR7B	2			G13	PR9B	2		C*
G12	PR4C	1		T	G12	PR7A	2			G12	PR9A	2		T*
G16	PR5B	1		C	G16	PR6D	2			G16	PR7D	2		C
F16	PR5A	1		T	F16	PR6C	2			F16	PR7C	2		T
F15	PR4B	1		C	F15	PR6B	2			F15	PR7B	2		C*
E15	PR4A	1		T	E15	PR6A	2			E15	PR7A	2		T*
E16	PR3B	1		C	E16	PR5D	2			E16	PR6D	2		C
D16	PR3A	1		T	D16	PR5C	2			D16	PR6C	2		T
VCCIO1	VCCIO1	1			VCCIO2	VCCIO2	2			VCCIO2	VCCIO2	2		
GND	GNDIO1	1			GND	GNDIO2	2			GND	GNDIO2	2		
D15	PR2D	1		C	D15	PR5B	2			D15	PR6B	2		C*
C15	PR2C	1		T	C15	PR5A	2			C15	PR6A	2		T*
C16	PR2B	1		C	C16	PR4D	2			C16	PR5D	2		C
B16	PR2A	1		T	B16	PR4C	2			B16	PR5C	2		T
F14	PR3D	1		C	F14	PR4B	2			F14	PR5B	2		C*
E14	PR3C	1		T	E14	PR4A	2			E14	PR5A	2		T*
-	-	-			-	-	-			GND	GND	-		
F12	NC				F12	PR3D	2			F12	PR4D	2		C
F13	NC				F13	PR3C	2			F13	PR4C	2		T
E12	NC				E12	PR3B	2			E12	PR4B	2		C*
E13	NC				E13	PR3A	2			E13	PR4A	2		T*
D13	NC				D13	PR2B	2			D13	PR3B	2		C*
D14	NC				D14	PR2A	2			D14	PR3A	2		T*
VCCIO0	VCCIO0	0			VCCIO2	VCCIO2	2			VCCIO2	VCCIO2	2		
GND	GNDIO0	0			GND	GNDIO2	2			GND	GNDIO2	2		
GND	GNDIO0	0			GND	GNDIO1	1			GND	GNDIO1	1		
VCCIO0	VCCIO0	0			VCCIO1	VCCIO1	1			VCCIO1	VCCIO1	1		
B15	NC				B15	PT11D	1			B15	PT16D	1		C
A15	NC				A15	PT11C	1			A15	PT16C	1		T
C14	NC				C14	PT11B	1			C14	PT16B	1		C
B14	NC				B14	PT11A	1			B14	PT16A	1		T
C13	PT9F	0		C	C13	PT10F	1			C13	PT15D	1		C
B13	PT9E	0		T	B13	PT10E	1			B13	PT15C	1		T

LCMxo2280 Logic Signal Connections: 324 ftBGA (Cont.)

LCMxo2280				
Ball Number	Ball Function	Bank	Dual Function	Differential
V10	PB9B	4		C
N10	PB9C	4		T
R10	PB9D	4		C
P10	PB10F	4	PCLK4_1***	C
T10	PB10E	4		T
U10	PB10D	4		C
V11	PB10C	4		T
U11	PB10B	4	PCLK4_0***	C
VCCIO4	VCCIO4	4		
GND	GNDIO4	4		
T11	PB10A	4		T
U12	PB11A	4		T
R11	PB11B	4		C
GND	GND	-		
T12	PB11C	4		T
P11	PB11D	4		C
V12	PB12A	4		T
V13	PB12B	4		C
R12	PB12C	4		T
N11	PB12D	4		C
U13	PB12E	4		T
VCCIO4	VCCIO4	4		
GND	GNDIO4	4		
V14	PB12F	4		C
T13	PB13A	4		T
P12	PB13B	4		C
R13	PB13C	4		T
N12	PB13D	4		C
V15	PB14A	4		T
U14	PB14B	4		C
V16	PB14C	4		T
GND	GND	-		
T14	PB14D	4		C
U15	PB15A	4		T
V17	PB15B	4		C
P13**	SLEEPN	-	SLEEPN	
T15	PB15D	4		
U16	PB16A	4		T
V18	PB16B	4		C
N13	PB16C	4		T
R14	PB16D	4		C
VCCIO4	VCCIO4	4		
GND	GNDIO4	4		

LCMxo2280 Logic Signal Connections: 324 ftBGA (Cont.)

LCMxo2280				
Ball Number	Ball Function	Bank	Dual Function	Differential
GND	GNDIO3	3		
VCCIO3	VCCIO3	3		
P15	PR20B	3		C
N14	PR20A	3		T
N15	PR19B	3		C
M13	PR19A	3		T
R15	PR18B	3		C*
T16	PR18A	3		T*
N16	PR17D	3		C
M14	PR17C	3		T
U17	PR17B	3		C*
VCC	VCC	-		
U18	PR17A	3		T*
R17	PR16D	3		C
R16	PR16C	3		T
P16	PR16B	3		C*
VCCIO3	VCCIO3	3		
GND	GNDIO3	3		
P17	PR16A	3		T*
L13	PR15D	3		C
M15	PR15C	3		T
T17	PR15B	3		C*
T18	PR15A	3		T*
L14	PR14D	3		C
L15	PR14C	3		T
R18	PR14B	3		C*
P18	PR14A	3		T*
GND	GND	-		
K15	PR13D	3		C
K13	PR13C	3		T
N17	PR13B	3		C*
N18	PR13A	3		T*
K16	PR12D	3		C
K14	PR12C	3		T
M16	PR12B	3		C*
L16	PR12A	3		T*
GND	GNDIO3	3		
VCCIO3	VCCIO3	3		
J16	PR11D	3		C
J14	PR11C	3		T
M17	PR11B	3		C*
L17	PR11A	3		T*
J15	PR10D	2		C

Part Number	LUTs	Supply Voltage	I/Os	Grade	Package	Pins	Temp.
LCMxo1200E-3T100C	1200	1.2V	73	-3	TQFP	100	COM
LCMxo1200E-4T100C	1200	1.2V	73	-4	TQFP	100	COM
LCMxo1200E-5T100C	1200	1.2V	73	-5	TQFP	100	COM
LCMxo1200E-3T144C	1200	1.2V	113	-3	TQFP	144	COM
LCMxo1200E-4T144C	1200	1.2V	113	-4	TQFP	144	COM
LCMxo1200E-5T144C	1200	1.2V	113	-5	TQFP	144	COM
LCMxo1200E-3M132C	1200	1.2V	101	-3	csBGA	132	COM
LCMxo1200E-4M132C	1200	1.2V	101	-4	csBGA	132	COM
LCMxo1200E-5M132C	1200	1.2V	101	-5	csBGA	132	COM
LCMxo1200E-3B256C	1200	1.2V	211	-3	caBGA	256	COM
LCMxo1200E-4B256C	1200	1.2V	211	-4	caBGA	256	COM
LCMxo1200E-5B256C	1200	1.2V	211	-5	caBGA	256	COM
LCMxo1200E-3FT256C	1200	1.2V	211	-3	ftBGA	256	COM
LCMxo1200E-4FT256C	1200	1.2V	211	-4	ftBGA	256	COM
LCMxo1200E-5FT256C	1200	1.2V	211	-5	ftBGA	256	COM

Part Number	LUTs	Supply Voltage	I/Os	Grade	Package	Pins	Temp.
LCMxo2280E-3T100C	2280	1.2V	73	-3	TQFP	100	COM
LCMxo2280E-4T100C	2280	1.2V	73	-4	TQFP	100	COM
LCMxo2280E-5T100C	2280	1.2V	73	-5	TQFP	100	COM
LCMxo2280E-3T144C	2280	1.2V	113	-3	TQFP	144	COM
LCMxo2280E-4T144C	2280	1.2V	113	-4	TQFP	144	COM
LCMxo2280E-5T144C	2280	1.2V	113	-5	TQFP	144	COM
LCMxo2280E-3M132C	2280	1.2V	101	-3	csBGA	132	COM
LCMxo2280E-4M132C	2280	1.2V	101	-4	csBGA	132	COM
LCMxo2280E-5M132C	2280	1.2V	101	-5	csBGA	132	COM
LCMxo2280E-3B256C	2280	1.2V	211	-3	caBGA	256	COM
LCMxo2280E-4B256C	2280	1.2V	211	-4	caBGA	256	COM
LCMxo2280E-5B256C	2280	1.2V	211	-5	caBGA	256	COM
LCMxo2280E-3FT256C	2280	1.2V	211	-3	ftBGA	256	COM
LCMxo2280E-4FT256C	2280	1.2V	211	-4	ftBGA	256	COM
LCMxo2280E-5FT256C	2280	1.2V	211	-5	ftBGA	256	COM
LCMxo2280E-3FT324C	2280	1.2V	271	-3	ftBGA	324	COM
LCMxo2280E-4FT324C	2280	1.2V	271	-4	ftBGA	324	COM
LCMxo2280E-5FT324C	2280	1.2V	271	-5	ftBGA	324	COM

Part Number	LUTs	Supply Voltage	I/Os	Grade	Package	Pins	Temp.
LCMxo2280C-3TN100C	2280	1.8V/2.5V/3.3V	73	-3	Lead-Free TQFP	100	COM
LCMxo2280C-4TN100C	2280	1.8V/2.5V/3.3V	73	-4	Lead-Free TQFP	100	COM
LCMxo2280C-5TN100C	2280	1.8V/2.5V/3.3V	73	-5	Lead-Free TQFP	100	COM
LCMxo2280C-3TN144C	2280	1.8V/2.5V/3.3V	113	-3	Lead-Free TQFP	144	COM
LCMxo2280C-4TN144C	2280	1.8V/2.5V/3.3V	113	-4	Lead-Free TQFP	144	COM
LCMxo2280C-5TN144C	2280	1.8V/2.5V/3.3V	113	-5	Lead-Free TQFP	144	COM
LCMxo2280C-3MN132C	2280	1.8V/2.5V/3.3V	101	-3	Lead-Free csBGA	132	COM
LCMxo2280C-4MN132C	2280	1.8V/2.5V/3.3V	101	-4	Lead-Free csBGA	132	COM
LCMxo2280C-5MN132C	2280	1.8V/2.5V/3.3V	101	-5	Lead-Free csBGA	132	COM
LCMxo2280C-3BN256C	2280	1.8V/2.5V/3.3V	211	-3	Lead-Free caBGA	256	COM
LCMxo2280C-4BN256C	2280	1.8V/2.5V/3.3V	211	-4	Lead-Free caBGA	256	COM
LCMxo2280C-5BN256C	2280	1.8V/2.5V/3.3V	211	-5	Lead-Free caBGA	256	COM
LCMxo2280C-3FTN256C	2280	1.8V/2.5V/3.3V	211	-3	Lead-Free ftBGA	256	COM
LCMxo2280C-4FTN256C	2280	1.8V/2.5V/3.3V	211	-4	Lead-Free ftBGA	256	COM
LCMxo2280C-5FTN256C	2280	1.8V/2.5V/3.3V	211	-5	Lead-Free ftBGA	256	COM
LCMxo2280C-3FTN324C	2280	1.8V/2.5V/3.3V	271	-3	Lead-Free ftBGA	324	COM
LCMxo2280C-4FTN324C	2280	1.8V/2.5V/3.3V	271	-4	Lead-Free ftBGA	324	COM
LCMxo2280C-5FTN324C	2280	1.8V/2.5V/3.3V	271	-5	Lead-Free ftBGA	324	COM

Part Number	LUTs	Supply Voltage	I/Os	Grade	Package	Pins	Temp.
LCMxo256E-3TN100C	256	1.2V	78	-3	Lead-Free TQFP	100	COM
LCMxo256E-4TN100C	256	1.2V	78	-4	Lead-Free TQFP	100	COM
LCMxo256E-5TN100C	256	1.2V	78	-5	Lead-Free TQFP	100	COM
LCMxo256E-3MN100C	256	1.2V	78	-3	Lead-Free csBGA	100	COM
LCMxo256E-4MN100C	256	1.2V	78	-4	Lead-Free csBGA	100	COM
LCMxo256E-5MN100C	256	1.2V	78	-5	Lead-Free csBGA	100	COM

Part Number	LUTs	Supply Voltage	I/Os	Grade	Package	Pins	Temp.
LCMxo640E-3TN100C	640	1.2V	74	-3	Lead-Free TQFP	100	COM
LCMxo640E-4TN100C	640	1.2V	74	-4	Lead-Free TQFP	100	COM
LCMxo640E-5TN100C	640	1.2V	74	-5	Lead-Free TQFP	100	COM
LCMxo640E-3MN100C	640	1.2V	74	-3	Lead-Free csBGA	100	COM
LCMxo640E-4MN100C	640	1.2V	74	-4	Lead-Free csBGA	100	COM
LCMxo640E-5MN100C	640	1.2V	74	-5	Lead-Free csBGA	100	COM
LCMxo640E-3TN144C	640	1.2V	113	-3	Lead-Free TQFP	144	COM
LCMxo640E-4TN144C	640	1.2V	113	-4	Lead-Free TQFP	144	COM
LCMxo640E-5TN144C	640	1.2V	113	-5	Lead-Free TQFP	144	COM
LCMxo640E-3MN132C	640	1.2V	101	-3	Lead-Free csBGA	132	COM
LCMxo640E-4MN132C	640	1.2V	101	-4	Lead-Free csBGA	132	COM
LCMxo640E-5MN132C	640	1.2V	101	-5	Lead-Free csBGA	132	COM
LCMxo640E-3BN256C	640	1.2V	159	-3	Lead-Free caBGA	256	COM
LCMxo640E-4BN256C	640	1.2V	159	-4	Lead-Free caBGA	256	COM
LCMxo640E-5BN256C	640	1.2V	159	-5	Lead-Free caBGA	256	COM
LCMxo640E-3FTN256C	640	1.2V	159	-3	Lead-Free ftBGA	256	COM
LCMxo640E-4FTN256C	640	1.2V	159	-4	Lead-Free ftBGA	256	COM
LCMxo640E-5FTN256C	640	1.2V	159	-5	Lead-Free ftBGA	256	COM